

EAST - [09935796b.wsp.1]

File View Edit Tools Window Help

☐ Drafts
☐ BRS: test\$3 and (pad adj damage)
☐ Pending
☒ Active
☐ L1: (9) testing adj probe\$1 and pad adj da
☐ L2: (0) testing adj probe\$1 and probing ad
☐ L3: (8) test\$3 and probing adj damage
☐ L4: (93) test\$3 and pad adj damage
☐ Failed
☒ Saved
☐ (2) ("5982042").PN.
☐ (2) ("6303948").PN.
☐ Favorites
☐ Tagged (0)
☐ UDC
☐ Queue
☐ Trash

DBs: ☐ Plurals

Default operator: ☒ Highlight all hit terms initially

☒ BRS1 ☐ I54R ☐ Image ☐ Text ☐ HTML

	U	I	Document ID	Issue Date	Pages	Title	Current OR	Current XRef
1	<input type="checkbox"/>	<input type="checkbox"/>	US 6651325 B2	20031125	8	Method for forming cantilever beam probe card and probe card formed	29/846	29/825; 29/847;
2	<input type="checkbox"/>	<input type="checkbox"/>	US 6650021 B2	20031118	23	Recessed bond pad	257/786	257/690; 257/758;
3	<input type="checkbox"/>	<input type="checkbox"/>	US 6632700 B1	20031014	11	Method to form a color image sensor cell while protecting the bonding pad structure	438/70	
4	<input type="checkbox"/>	<input type="checkbox"/>	US 6621262 B2	20030916	10	Method for optimizing probe card analysis and scrub mark analysis data	324/158.1	324/754; 324/765;
5	<input type="checkbox"/>	<input type="checkbox"/>	US 6590294 B1	20030708	8	Device for bump probing and method of fabrication	257/781	257/692; 257/780;
6	<input type="checkbox"/>	<input type="checkbox"/>	US 6578264 B1	20030617	36	Method for constructing a membrane probe using a depression	29/874	29/426.1; 29/846;
7	<input type="checkbox"/>	<input type="checkbox"/>	US 6538264 B2	20030325	18	Semiconductor reliability test chip	257/48	257/202; 257/203;
8	<input type="checkbox"/>	<input type="checkbox"/>	US 6525982 B1	20030225	11	Methods of programming and circuitry for a programmable element	365/225.7	365/203
9	<input type="checkbox"/>	<input type="checkbox"/>	US 6495917 B1	20021217	22	Method and structure of column interconnect	257/758	257/752; 257/760;
10	<input type="checkbox"/>	<input type="checkbox"/>	US 6448650 B1	20020910	8	Fine pitch system and method for reinforcing bond pads in semiconductor	257/758	257/750; 257/763;
11	<input type="checkbox"/>	<input type="checkbox"/>	US 6437584 B1	20020820	24	Membrane probing system with local contact scrub	324/754	324/765